

| Type number | Package | Package description | Total product weight |
|--------------|-----------|---------------------|----------------------|
| 74AUP1G14GX4 | SOT1269-2 | X2SON4 | 0.36986 mg |

| 12NC | Version | Pb-free soldering | | | Pb soldering | | | Number of processing cycles | Assembly site | RHF-indicator |
|--------------|---------|-------------------|-----|------|--------------|-----|------|-----------------------------|--------------------------------------------------------------|---------------|
| | | MSL | PPT | MPPT | MSL | PPT | MPPT | | | |
| 935340116147 | 4 | 1 | 260 | 30 s | 1 | 240 | 20 s | 3 | Bangkok, Thailand; Shanghai, China; Seremban, Malaysia | |

| Subpart | Material group | Substances | CAS number | Mass(mg) | Mass(%) of subpart | Mass(%) of total product |
|----------------|------------------|---------------------------------------------------|-------------|-----------|--------------------|--------------------------|
| Die | Doped silicon | Silicon (Si) | 7440-21-3 | 0.01820 | 100.00000 | 4.92065 |
| | | subTotal | | 0.01820 | 100.00000 | 4.92065 |
| Component | Additive | Non hazardous | Proprietary | 0.00010 | 5.00000 | 0.02704 |
| | Filler | Bisphenol-A/Epichlorohydrin Epoxy resin (generic) | 25068-38-6 | 0.00010 | 5.00000 | 0.02704 |
| | | Silica -amorphous- | 7631-86-9 | 0.00100 | 50.00000 | 0.27037 |
| | | Epoxy resin system | Proprietary | 0.00060 | 30.00000 | 0.16222 |
| | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 0.00020 | 10.00000 | 0.05407 |
| | | subTotal | | | 0.00200 | 100.00000 |
| Lead Frame | Copper alloy | Copper (Cu) | 7440-50-8 | 0.13097 | 93.54790 | 35.40990 |
| | | Magnesium (Mg) | 7439-95-4 | 0.00020 | 0.14590 | 0.05523 |
| | | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 0.00408 | 2.91730 | 1.10426 |
| | | Silicon (Si) | 7440-21-3 | 0.00088 | 0.63210 | 0.23926 |
| | Pure metal layer | Gold (Au) | 7440-57-5 | 0.00008 | 0.05830 | 0.02207 |
| | | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 0.00352 | 2.51720 | 0.95281 |
| | | Palladium (Pd) | 7440-05-3 | 0.00025 | 0.18130 | 0.06863 |
| subTotal | | | 0.14000 | 100.00000 | 37.85216 | |
| Mould Compound | Additive | Misc. Phosphor compounds (generic) | 7723-14-0 | 0.00020 | 0.10000 | 0.05516 |
| | | Non hazardous | Proprietary | 0.00734 | 3.60000 | 1.98562 |
| | Filler | Silica fused | 60676-86-0 | 0.17952 | 88.00000 | 48.53728 |
| | Pigment | Carbon black | 1333-86-4 | 0.00041 | 0.20000 | 0.11031 |
| | | Phenolic resin | Proprietary | 0.00836 | 4.10000 | 2.26140 |
| | Polymer | Tetramethylbiphenyl diglycidyl ether | 85954-11-6 | 0.00816 | 4.00000 | 2.20624 |
| subTotal | | | 0.20400 | 100.00000 | 55.15601 | |
| Wire | Impurity | Non hazardous | Proprietary | 0.00000 | 0.01000 | 0.00015 |
| | Pure metal | Copper (Cu) | 7440-50-8 | 0.00546 | 96.49000 | 1.47693 |
| | Pure metal layer | Gold (Au) | 7440-57-5 | 0.00003 | 0.50000 | 0.00765 |
| | | Palladium (Pd) | 7440-05-3 | 0.00017 | 3.00000 | 0.04592 |
| subTotal | | | 0.00566 | 100.00000 | 1.53065 | |

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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